

Title (en)

METHOD OF MAKING SPUTTERING TARGET AND TARGET PRODUCED

Title (de)

VERFAHREN ZUR HERSTELLUNG EINES SPUTTERTARGETS UND HERGESTELLTES TARGET

Title (fr)

PROCÉDÉ DE PRODUCTION D'UNE CIBLE DE PULVÉRISATION ET CIBLE AINSI PRODUITE

Publication

EP 2043800 A2 20090408 (EN)

Application

EP 07796745 A 20070709

Priority

- US 2007015654 W 20070709
- US 83152106 P 20060717

Abstract (en)

[origin: US2008011392A1] Method of making a sputtering target includes the steps of melting a metallic target material, controlling the temperature of the melted target material in a manner that the melted target material has almost no superheat, introducing the melted target material into a mold having interior walls forming a mold cavity in the shape of the desired target, and solidifying the melted target material in the mold by extracting heat therefrom at a rate to solidify it to form a sputtering target having a cellular nondendritic microstructure uniformly throughout the target. A sputtering target is provided comprising a metallic target material having a substantially equiaxed, cellular nondendritic microstructure uniformly throughout the target.

IPC 8 full level

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CPC (source: EP US)

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